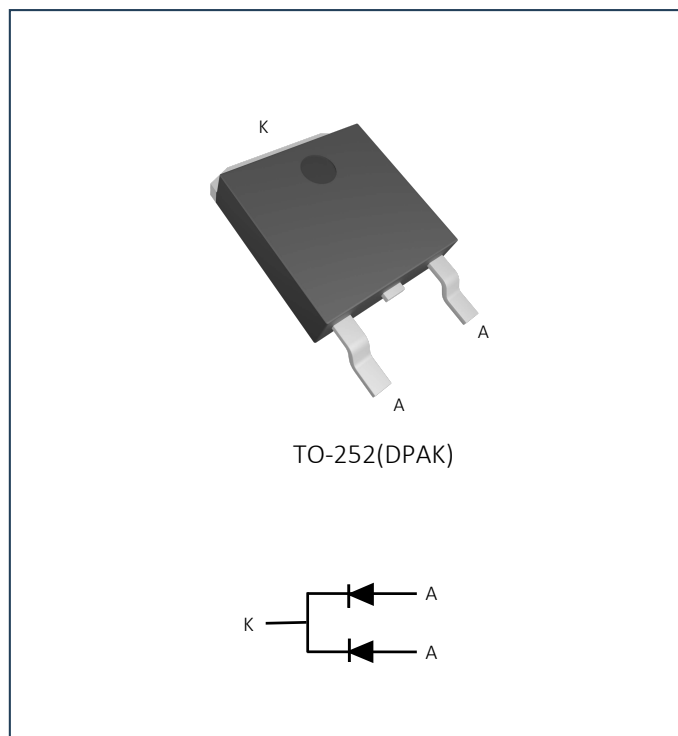


DSEK16S06B

超快软恢复特性二极管整流器

Ultra Soft Recovery Rectifier

封装外形 Package



主要参数 Device summary

Symbol	Value
$I_F(AV)$	16A
V_{RRM}	600V
$V_F(typ)$	1.15V@8A 125°C
$I_R(typ)$	0.05mA@600V 125°C
$T_{j(max)}$	175°C

机械数据 Mechanical Data

- 模塑料符合 UL 94 V-0 易燃等级, 符合 RoHS 标准
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- 端子: 镀锡引线, 可焊接 J-STD-002 和 JESD22-B102
Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- 极性: 本体标记
Polarity: As marked on body

产品特点 Features

- 超软恢复时间 Ultra soft recovery times
- 超快恢复时间 Ultra-fast recovery time
- 低正向压降 Low forward voltage
- 高结温 High Junction temperature
- 低漏电 Low leakage current
- 高可靠性 High reliability
- 环保产品 RoHS product

最大额定值 Maximum ratings

项目 Parameter	符合 Symbol	数值 Value	单位 Unit
反向电压 Peak repetitive reverse voltage	V_{RRM}	600	V
平均正向电流 Average forward current	$I_{F(AV)}$	16	A
	per diode	8	A
浪涌电流 Non-repetitive single pulse surge current $t=8.3ms$	I_{FSM}	90	A
结温 Junction temperature	T_j	-55~+175	°C
存储温度 Storage temperature	T_{STG}	-55~+175	°C

电特性 Electrical characteristics($T_c=25^{\circ}C$)

项目 Parameter	测试条件 Tests conditions	数值 Value	单位 Unit
反向电压 V_{RRM}	$I_R=0.05mA$	600	V
反向漏电流 I_R	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$ $V_R=V_{RRM}$	- - -	0.03 0.3 mA
正向电压 V_F	$T_j=25^{\circ}C$ $T_j=125^{\circ}C$ $I_F=8A$ $I_F=1A$ $I_F=4A$ $I_F=8A$	- - - 0.76 1.00 1.15	1.6 V
反向恢复时间 T_{rr}	$T_j=25^{\circ}C$ Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$	- -	35 nS

热特性 Thermal characteristics($T_c=25^{\circ}C$)

项目 Parameter	符合 Symbol	数值 Value	单位 Unit
热阻 Thermal resistance from junction to case	$R_{th(j-c)}$	3.5	°C/W

典型特征曲线图 Typical Characteristic Curve

图 1: 正向电流与外壳温度

FIG 1: I_F - T_c

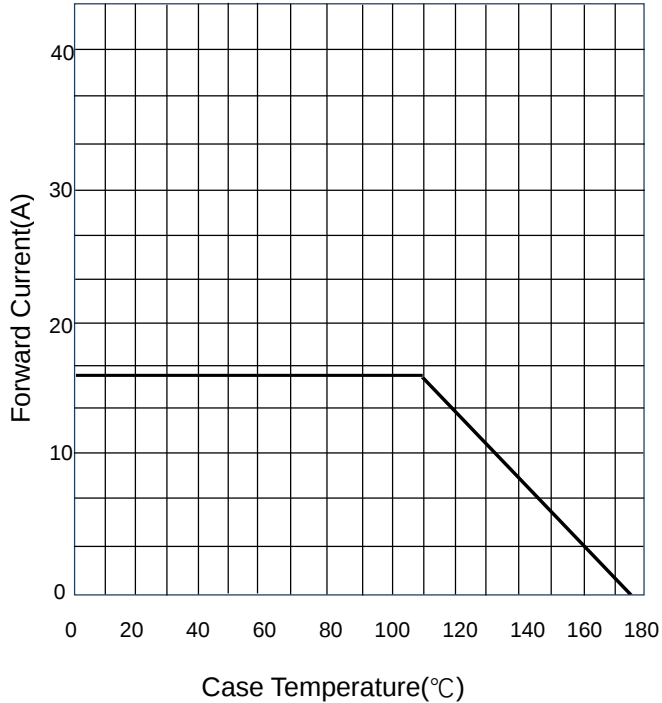


图 2: 正向浪涌循环次数

FIG 2: Surge Forward Current Capability

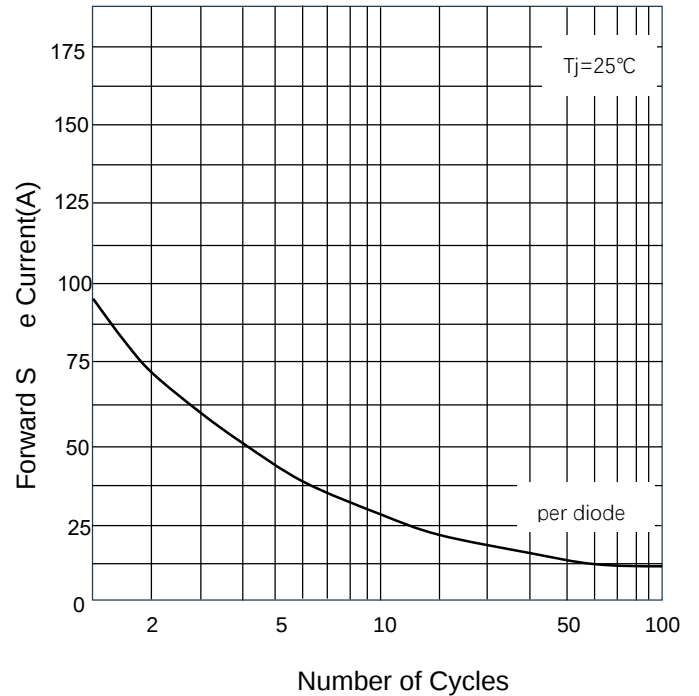


图 3: 反向电压与反向电流

FIG 3: V_R - I_R

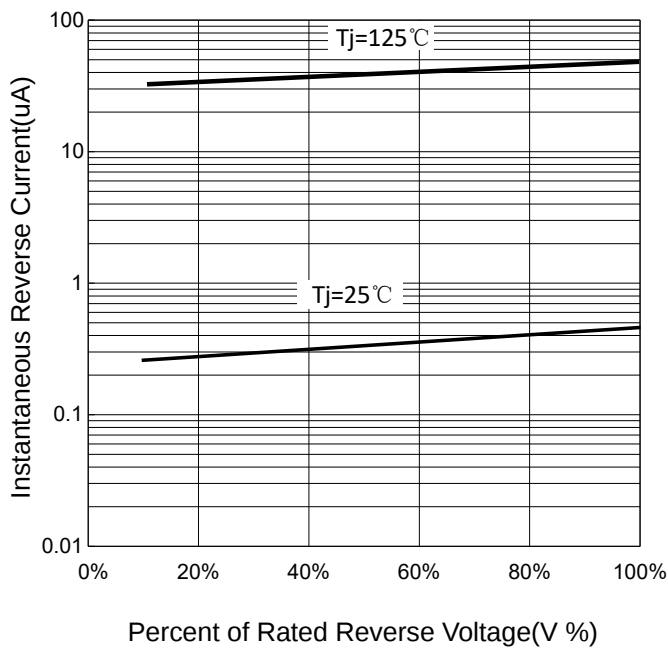
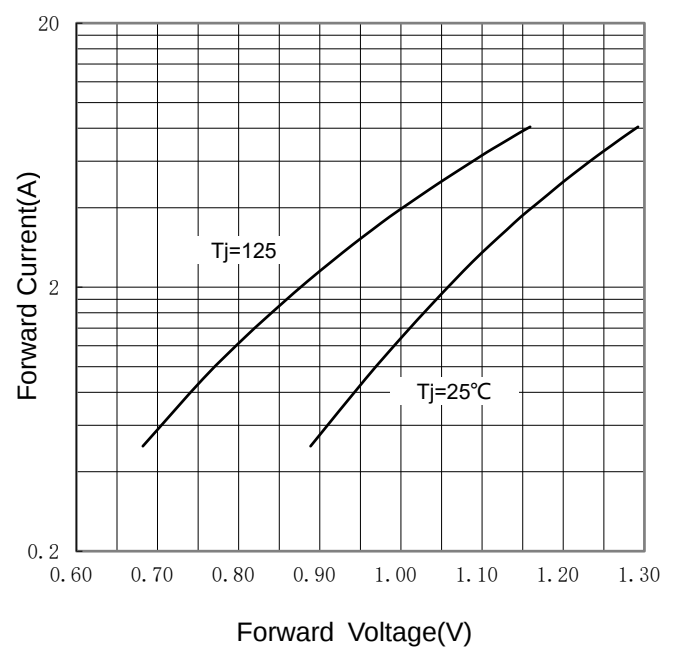


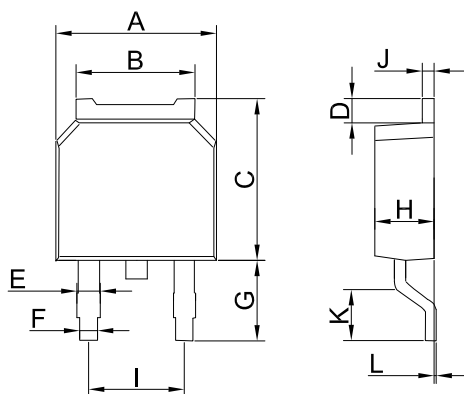
图 4: 正向电流与正向电压

FIG 4: I_F - V_F



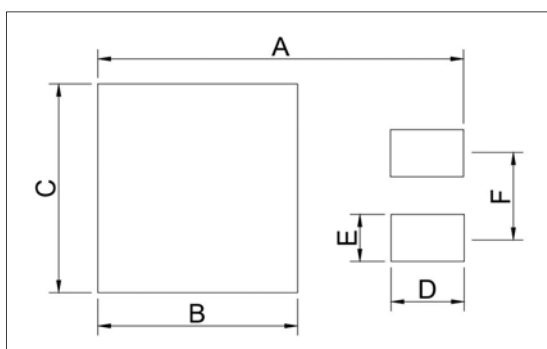
外形尺寸图及焊盘布局参考 Outline Dimensions and Pad Layout Reference

TO-252(DPAK)



Dim	Min	Typ	Max
A	6.30	6.45	6.60
B	5.20	5.40	5.60
C	6.80	7.00	7.20
D	0.60	0.80	1.00
E	0.60	0.70	0.80
F	0.50	0.60	0.70
G	2.70	2.90	3.10
H	2.20	2.30	2.40
I	4.45	4.60	4.75
J	0.45	0.50	0.55
K	1.25	1.50	1.75
L	0.00	0.10	0.20

尺寸单位: (mm)
Dimensions in millimeters



Dim	Millimet
A	11.4
B	6.23
C	6.74
D	2.28
E	1.52
F	4.56

订购信息 Ordering Information

订单型号 Order code	印记 Marking	封装 Package	重量 Weight (g)	包装形式 Packing	基本包装 Base qty (pcs)	盒 Box (pcs)	箱 Carton (pcs)
WDSEK16S06B000R	DSEK16S06B	TO-252(DPAK)	0.27	盘装 Reel	2500	2500	25000

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